

PZT751T1G, SPZT751T1G

PNP Silicon Planar Epitaxial Transistor

This PNP Silicon Epitaxial transistor is designed for use in industrial and consumer applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

Features

- High Current: 2.0 A
- The SOT-223 Package can be soldered using wave or reflow.
- SOT-223 package ensures level mounting, resulting in improved thermal conduction, and allows visual inspection of soldered joints. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die
- NPN Complement is PZT651T1
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
|---|-----------|------------|---------------------------|
| Collector-Emitter Voltage | V_{CEO} | 60 | Vdc |
| Collector-Base Voltage | V_{CBO} | 80 | Vdc |
| Emitter-Base Voltage | V_{EBO} | 5.0 | Vdc |
| Collector Current | I_C | 2.0 | Adc |
| Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1) Derate above 25°C | P_D | 0.8 6.4 | W mW/ $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | -65 to 150 | $^\circ\text{C}$ |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |

THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|---|-----------------|-----------|---------------------------|
| Thermal Resistance from Junction-to-Ambient in Free Air | $R_{\theta JA}$ | 156 | $^\circ\text{C}/\text{W}$ |
| Maximum Temperature for Soldering Purposes Time in Solder Bath | T_L | 260 10 | $^\circ\text{C}$ Sec |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Device mounted on a FR-4 glass epoxy printed circuit board using minimum recommended footprint.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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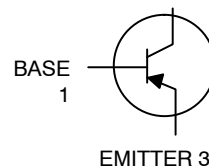
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SOT-223 PACKAGE HIGH CURRENT PNP SILICON TRANSISTOR SURFACE MOUNT

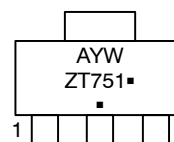


SOT-223
CASE 318E
STYLE 1

COLLECTOR 2, 4



MARKING DIAGRAM



A = Assembly Location
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|------------|----------------------|---------------------|
| PZT751T1G | SOT-223 (Pb-Free) | 1,000 / Tape & Reel |
| SPZT751T1G | SOT-223 (Pb-Free) | 1,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristics | Symbol | Min | Max | Unit |
|--|----------------------|----------------------|------------------|------------------|
| OFF CHARACTERISTICS | | | | |
| Collector–Emitter Breakdown Voltage (I _C = 10 mA _{dc} , I _B = 0) | V _{(BR)CEO} | 60 | – | V _{dc} |
| Collector–Emitter Breakdown Voltage (I _C = 100 μA _{dc} , I _E = 0) | V _{(BR)CBO} | 80 | – | V _{dc} |
| Emitter–Base Breakdown Voltage (I _E = 10 μA _{dc} , I _C = 0) | V _{(BR)EBO} | 5.0 | – | V _{dc} |
| Base–Emitter Cutoff Current (V _{EB} = 4.0 V _{dc}) | I _{EBO} | – | 0.1 | μA _{dc} |
| Collector–Base Cutoff Current (V _{CB} = 80 V _{dc} , I _E = 0) | I _{CBO} | – | 100 | nA _{dc} |
| ON CHARACTERISTICS (Note 2) | | | | |
| DC Current Gain (I _C = 50 mA _{dc} , V _{CE} = 2.0 V _{dc}) (I _C = 500 mA _{dc} , V _{CE} = 2.0 V _{dc}) (I _C = 1.0 A _{dc} , V _{CE} = 2.0 V _{dc}) (I _C = 2.0 A _{dc} , V _{CE} = 2.0 V _{dc}) | h _{FE} | 75 75 75 40 | – – – – | – |
| Collector–Emitter Saturation Voltages (I _C = 2.0 A _{dc} , I _B = 200 mA _{dc}) (I _C = 1.0 A _{dc} , I _B = 100 mA _{dc}) | V _{CE(sat)} | – – | 0.5 0.3 | V _{dc} |
| Base–Emitter Voltages (I _C = 1.0 A _{dc} , V _{CE} = 2.0 V _{dc}) | V _{BE(on)} | – | 1.0 | V _{dc} |
| Base–Emitter Saturation Voltage (I _C = 1.0 A _{dc} , I _B = 100 mA _{dc}) | V _{BE(sat)} | – | 1.2 | V _{dc} |
| Current–Gain–Bandwidth (I _C = 50 mA _{dc} , V _{CE} = 5.0 V _{dc} , f = 100 MHz) | f _T | 75 | – | MHz |

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle = 2.0%.

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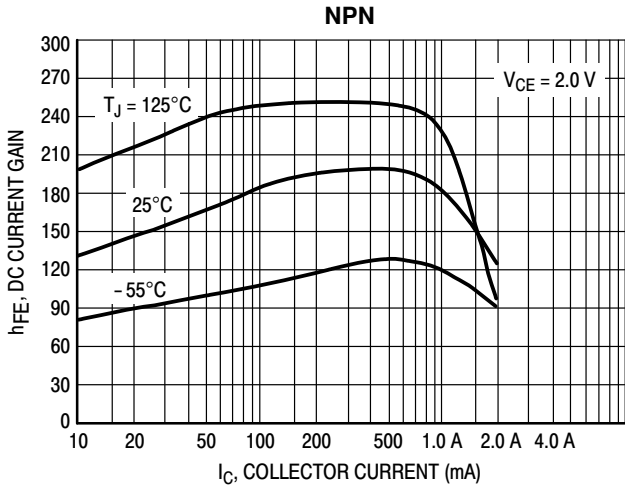


Figure 1. Typical DC Current Gain

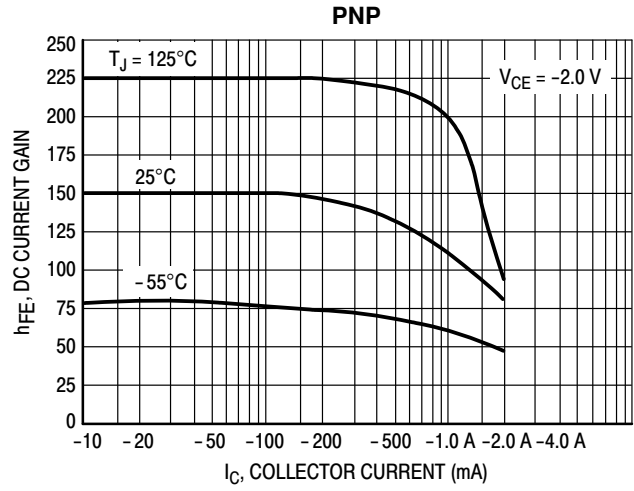


Figure 2. Typical DC Current Gain

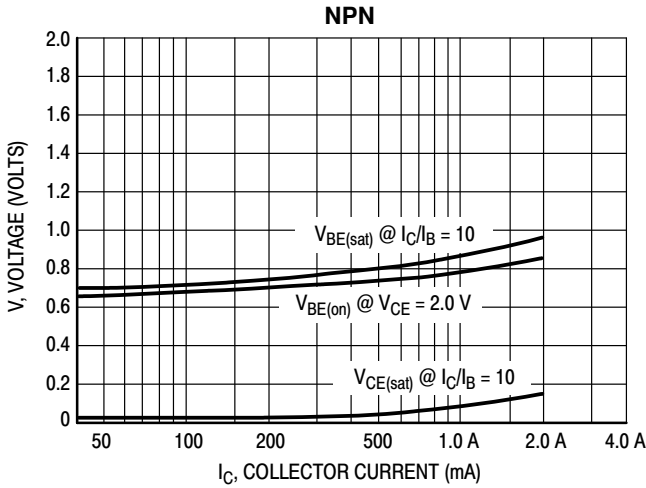


Figure 3. On Voltages

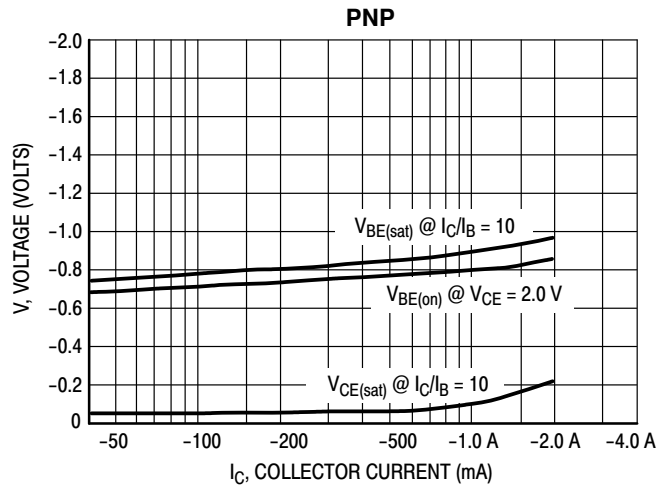


Figure 4. On Voltages

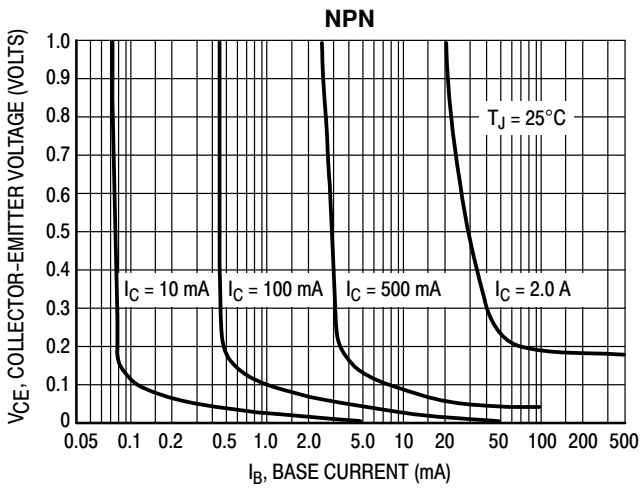


Figure 5. Collector Saturation Region

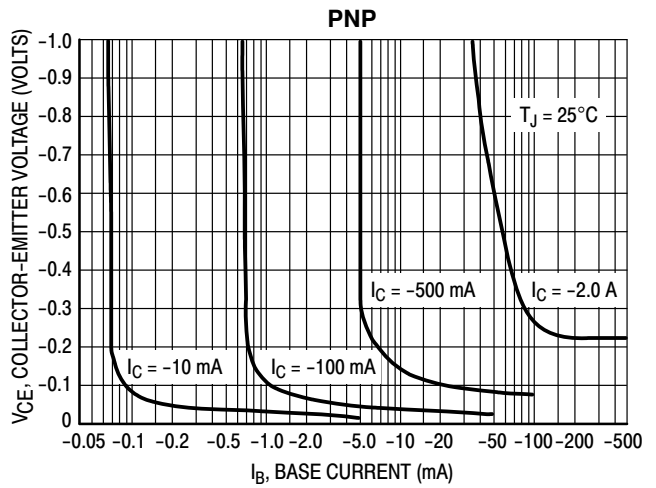
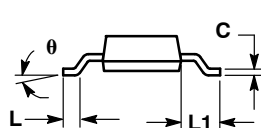
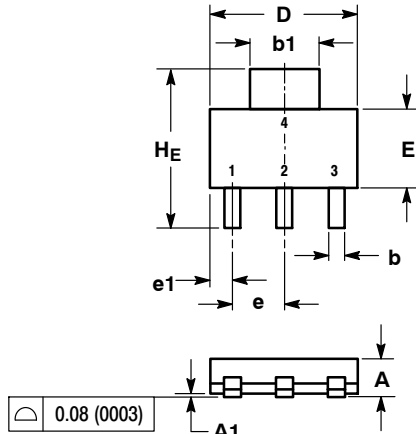


Figure 6. Collector Saturation Region

PZT751T1G, SPZT751T1G

PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE N

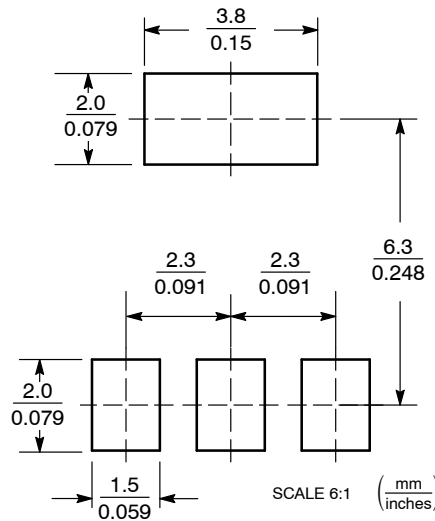


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.50 | 1.63 | 1.75 | 0.060 | 0.064 | 0.068 |
| A1 | 0.02 | 0.06 | 0.10 | 0.001 | 0.002 | 0.004 |
| b | 0.60 | 0.75 | 0.89 | 0.024 | 0.030 | 0.035 |
| b1 | 2.90 | 3.06 | 3.20 | 0.115 | 0.121 | 0.126 |
| c | 0.24 | 0.29 | 0.35 | 0.009 | 0.012 | 0.014 |
| D | 6.30 | 6.50 | 6.70 | 0.249 | 0.256 | 0.263 |
| E | 3.30 | 3.50 | 3.70 | 0.130 | 0.138 | 0.145 |
| e | 2.20 | 2.30 | 2.40 | 0.087 | 0.091 | 0.094 |
| e1 | 0.85 | 0.94 | 1.05 | 0.033 | 0.037 | 0.041 |
| L | 0.20 | --- | --- | 0.008 | --- | --- |
| L1 | 1.50 | 1.75 | 2.00 | 0.060 | 0.069 | 0.078 |
| HE | 6.70 | 7.00 | 7.30 | 0.264 | 0.276 | 0.287 |
| θ | 0° | - | 10° | 0° | - | 10° |

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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